12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260618000.1
Qualification of RFAB as an additional Fab site and CDAT as an additional Assembly site options for select devices
Change Notification / Sample Request

Date: June 18, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260618000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	**CUSTOMER PART NUMBER**
TLV7011DCKT	NULL
TCA6424ARGJR	TCA6424ARGJR
TCA6408APWR	TCA6408APWR
TPS22925BYPHR	TPS22925BYPHR
TCA6408ARGTR	TCA6408ARGTR
TLV7031DPWR	NULL
TPS22925CNYPHR	TPS22925CNYPHR
TPS22925CYPHT	TPS22925CYPHT
TPS22925BYPHT	TPS22925BYPHT
TPS22925CYPHR	TPS22925CYPHR
TLV7011DCKR	NULL
TCA6408ARSVR	TCA6408ARSVR
TPS22925BNYPHR	TPS22925BNYPHR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260618000.1	**PCN Date:**	June 18, 2026
Title:	Qualification of RFAB as an additional Fab site and CDAT as an additional Assembly site options for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	September 16, 2026	**Sample requests accepted until:**	August 17, 2026*

***Sample requests received after** August 17, 2026 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/ Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & CDAT as additional Assembly/Test site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
FFAB	LBC7	200mm	RFAB	LBC7	300mm

Construction differences are as follows:

Group 1 device (Fab only)

Group 2 device (Fab, Assembly site)

	Current site	Additional Site
Assembly site	TFME	CDAT
Wire diam/type	0.80mil Au	0.80mil Cu
Mount compound	SID# A-03	4207123
Mold compound	SID# R-07	4222198
Lead finish	NiPdAu	Matte Sn
Marking differences	Pin 1 stripe	Pin 1 dot
MSL level	2	1

Group 3 device (Fab, Assembly site)

	Current site	Additional Site
Assembly site	CARZ	CDAT
Wire diam/type	0.70mil Au	0.80mil Cu
Mount compound	SID#439825	4221460
Mold compound	SID#441141	4222198

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	**REACH**	**Green Status**	**IEC 62474**
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

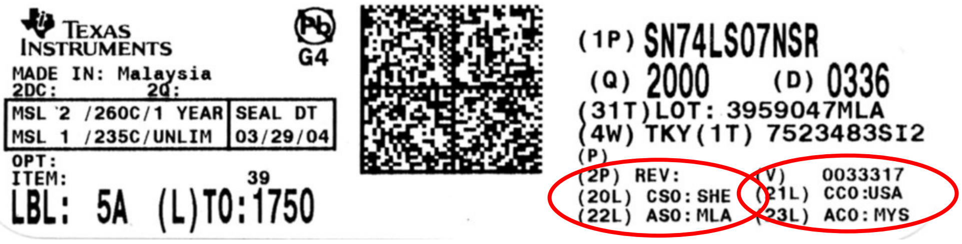
Wafer Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CARZ	CSZ	CHN	Jiangsu
TFME	NFM	CHN	Chongchuan
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS

G4

MADE IN: Malaysia

2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:

ITEM: 39

LBL: 5A (L)TO:1750

(1P) SN74LS07NSR

(Q) 2000 (D) 0336

(31T)LOT: 3959047MLA

(4W) TKY(1T) 7523483SI2

(P)

(2P) REV: (V) 0033317

(20L) CSO: SHE (21L) CCO:USA

(22L) ASO: MLA (23L) ACO: MYS

Group 1 Product Affected: (Fab only)

TCA6408APWR	TPS22925BNYPHR	TPS22925CNYPHT
TCA6408ARGTR	TPS22925BNYPHT	TPS22925CYPHR
TCA6408ARSVR	TPS22925BYPHR	TPS22925CYPHT
TCA6424ARGJR	TPS22925BYPHT	TPS22934YZVT
TCA6424ARGJRG4	TPS22925CNYPHR	

Group 2 Product Affected: (Fab, Assembly site)

TLV7011DCKR	TLV7011DCKT

Group 3 Product Affected: (Fab, Assembly site)

TLV7031DPWR

Qualification Report
LBC7 FFAB to RFAB Offload
Approve Date 15-April-2026

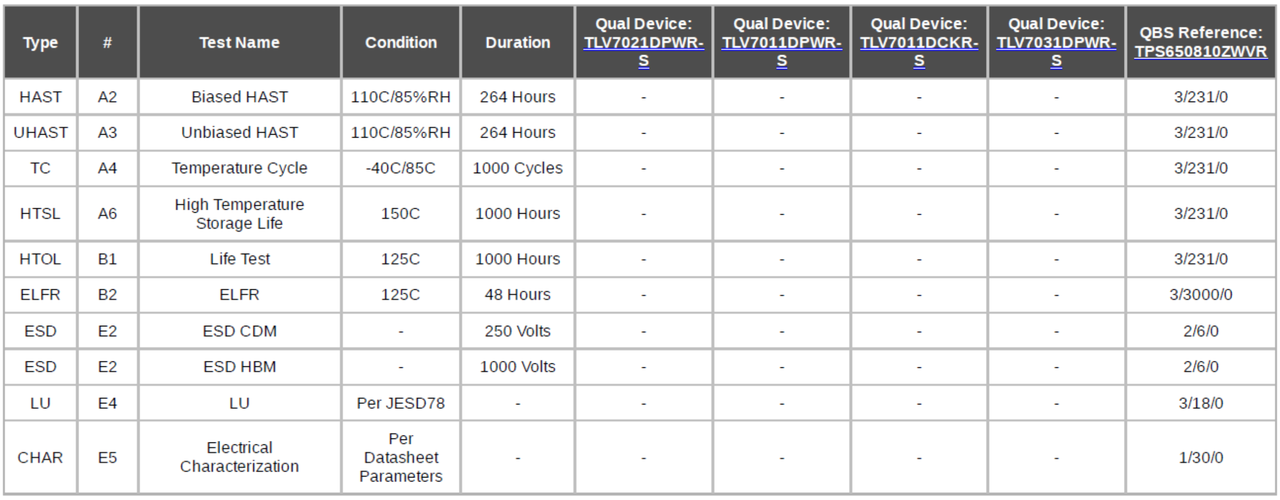
Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TCA6424ARGJR	QBS Process Reference: TPS650810ZWVR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	3/231/0
TC	A4	Temperature Cycle	-40C/85C	1000 Cycles	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0
ESD	E2	ESD CDM	-	250 Volts	-	2/6/0
ESD	E2	ESD HBM	-	1000 Volts	-	2/6/0
LU	E4	LU	Per JESD78	-	-	3/18/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TCA6424ARGJR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-063

Qualification Report
Approve Date 12-MAY -2025

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed



Type	#	Test Name	Condition	Duration	Qual Device: TLV7021DPWR-S	Qual Device: TLV7011DPWR-S	Qual Device: TLV7011DCKR-S	Qual Device: TLV7031DPWR-S	QBS Reference: TPS650810ZWVR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-40C/85C	1000 Cycles	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	-	3/3000/0
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	2/6/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	2/6/0
LU	E4	LU	Per JESD78	-	-	-	-	-	3/18/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TLV7021DPWR-S is qualified at MSL1 260C
Qual Device TLV7011DPWR-S is qualified at MSL1 260C
Qual Device TLV7011DCKR-S is qualified at MSL2 260C
Qual Device TLV7031DPWR-S is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2403-097

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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